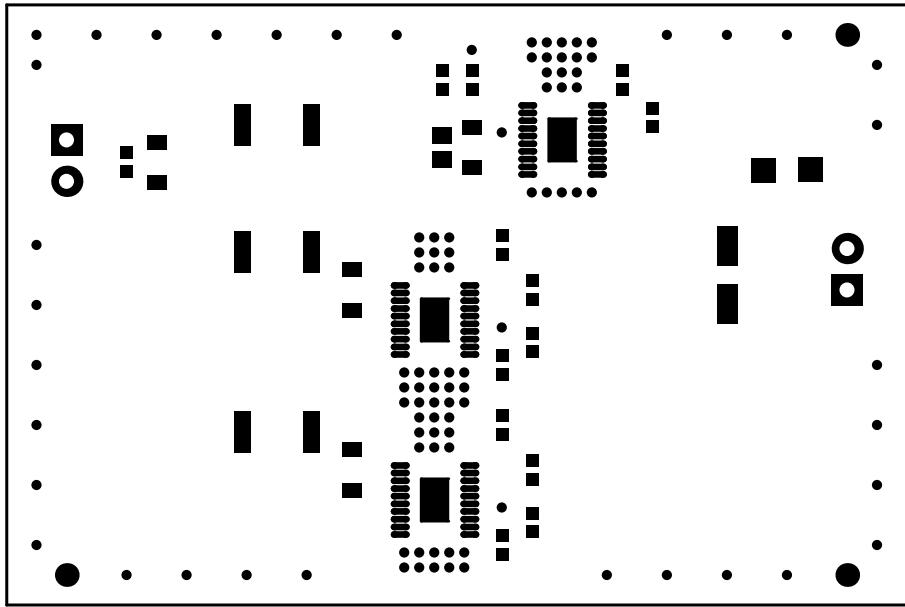
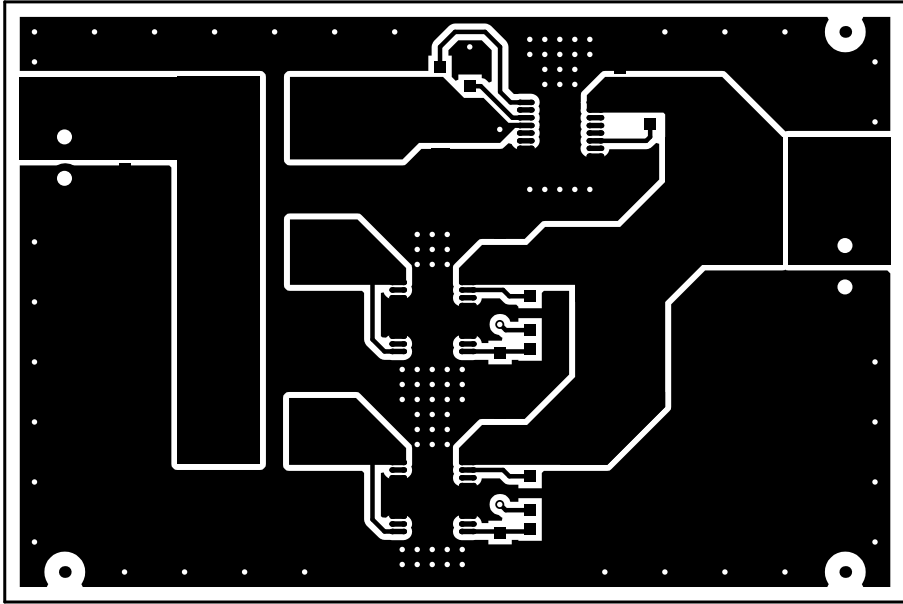


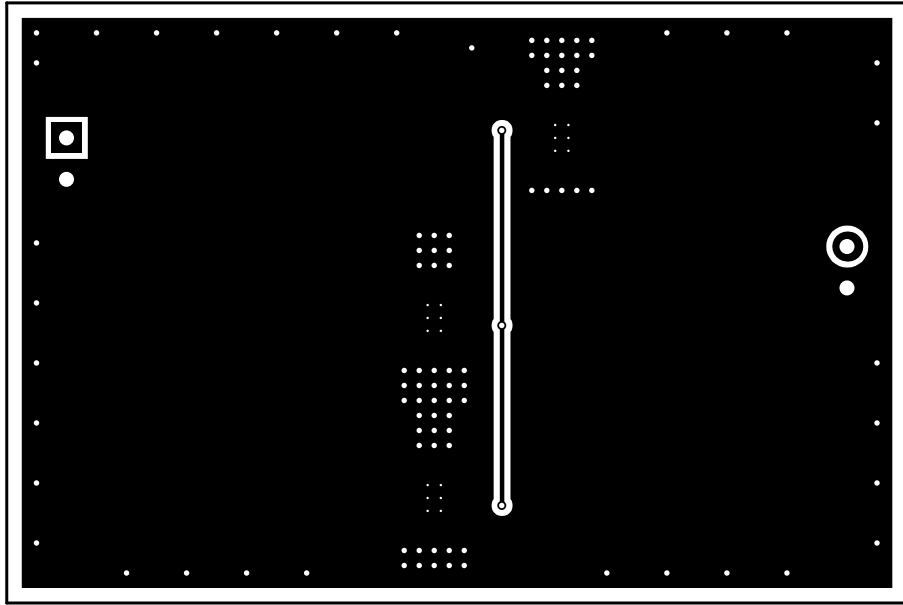
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00863	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/10/15	19:41:16	TEXAS INSTRUMENTS



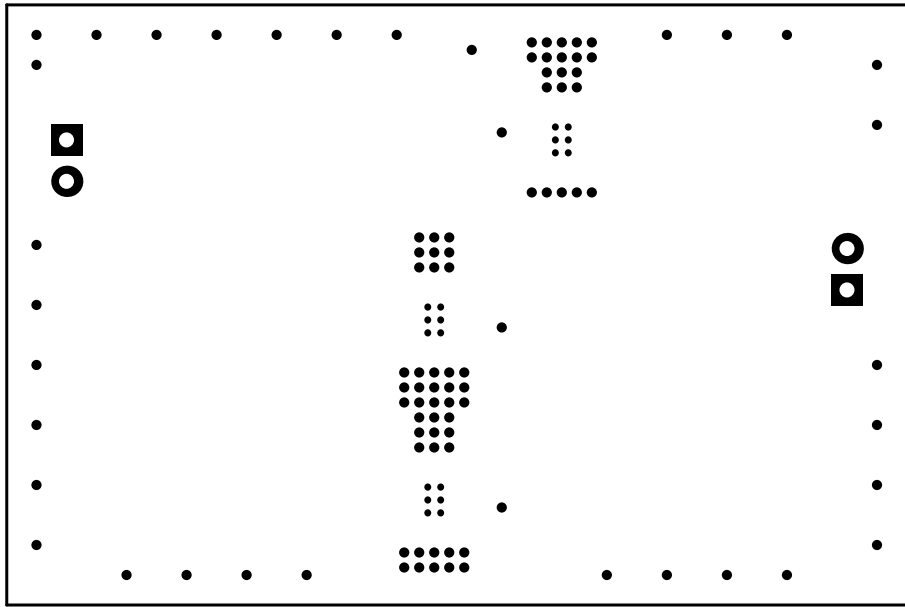
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00863	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/10/15 19:41:17	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00863	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/10/15 19:41:18	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00863	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/10/15 19:41:18	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00863

REV: A

SUN REV: Not In VersionControl

LAYER NAME = Bottom Solder

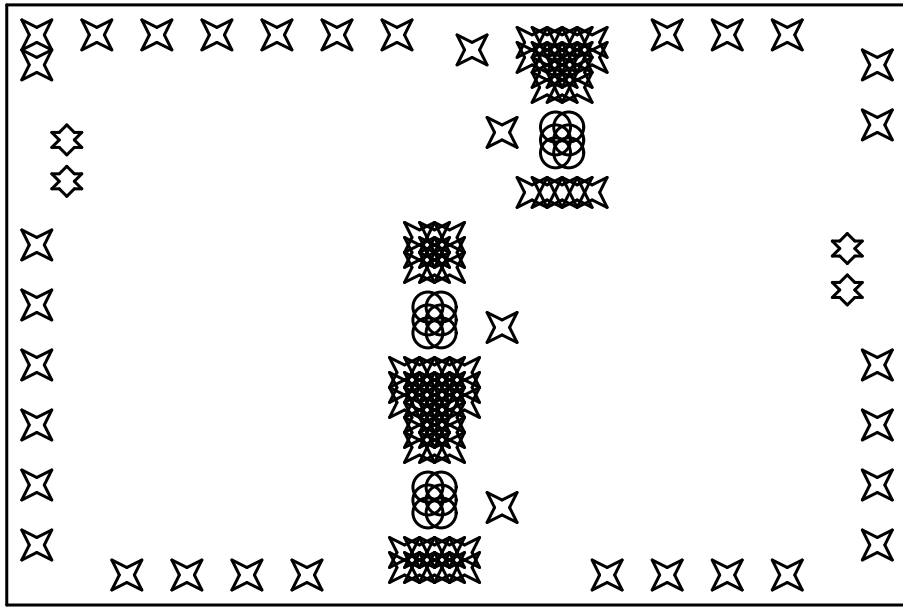
PLOT NAME = Bottom Solder Mask

GENERATED : 11/10/15 19:41:19

TEXAS INSTRUMENTS

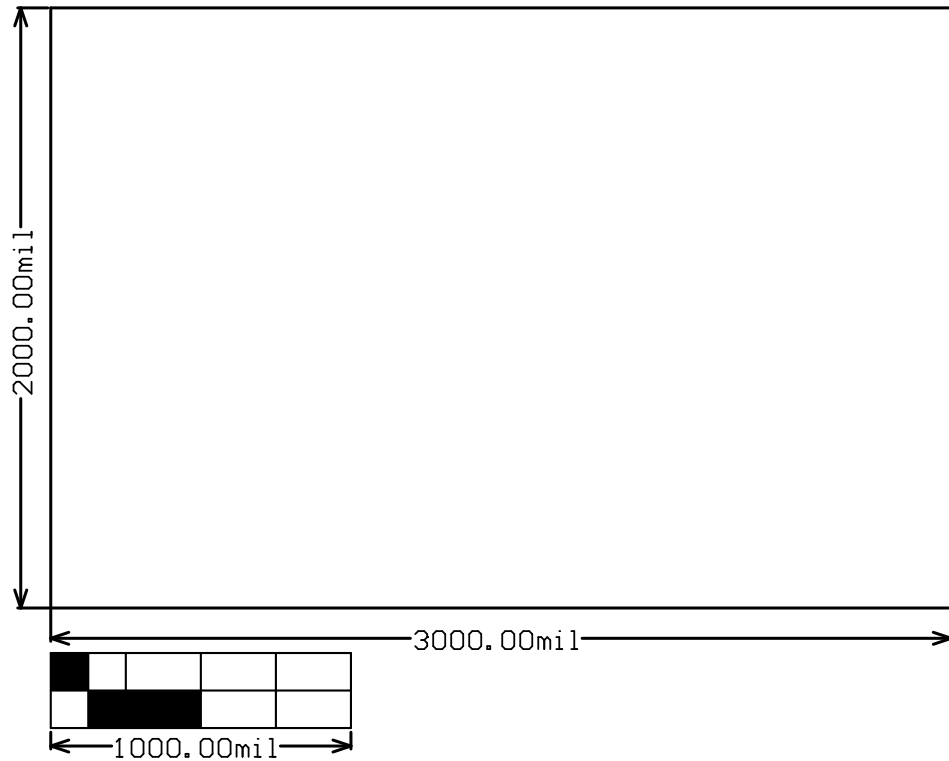


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00863	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/10/15	19:41:20	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	18	7.87mil (0.200mm)	PTH	Round
✧	99	18.00mil (0.457mm)	PTH	Round
✳	4	50.00mil (1.270mm)	PTH	Round
	121 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00863	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/10/15	19:41:20	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00863	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 11/10/15	19:41:21	TEXAS INSTRUMENTS

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